

L Number	Hits	Search Text	DB	Time stamp
1	6629	((copper or cu) near3 (layer or film or panel or coating)) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 16:47
2	4694	((copper or cu) near3 (layer or film or panel or coating)) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5)) and ((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 16:57
3	1533	((copper or cu) near3 (layer or film or panel or coating)) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5)) and ((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5))) and (circuit adj board\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 16:50
4	1020	((copper or cu) near3 (layer or film or panel or coating)) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5)) and ((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5))) and (circuit adj board\$3)) and (mask\$5 or resist or photomask\$5 or photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:06
5	161	((copper or cu) near3 (layer or film or panel or coating)) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5)) and ((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 cavit\$5))) and (circuit adj board\$3)) and (mask\$5 or resist or photomask\$5 or photoresist)) and ((layer or film or coating or panel) near5 (cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:05
6	19698	((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (laser or drill\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:03
7	1118	((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (laser or drill\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5))) and (circuit adj board\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 16:59
8	7	((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (laser or drill\$5) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5))) and (circuit adj board\$3)) and ((layer or film or coating or panel) near5 (cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:00
9	993673	(dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:04

10	73388	((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5)) and (circuit adj board\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:04
11	19413	((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5)) and (circuit adj board\$3)) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:05
12	1924	((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5)) and (circuit adj board\$3)) and copper) and ((layer or film or coating or panel) near5 (cathode or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:05
13	1229	((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5)) and (circuit adj board\$3)) and copper) and ((layer or film or coating or panel) near5 (cathode or electrode))) and (mask\$5 or resist or photomask\$5 or photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:06
15	93	((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5)) and (circuit adj board\$3)) and copper) and ((layer or film or coating or panel) near5 (cathode or electrode))) and (mask\$5 or resist or photomask\$5 or photoresist)) and blind	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:07
14	121	((dielectric or base or core or board or insulat\$5 or non\$2conduct\$5 or epoxy or polymer\$3 or resin\$5 or body) near5 (via\$3 or hole\$3 or trench\$3 or opening\$3 or cavit\$5)) and (circuit adj board\$3)) and copper) and ((layer or film or coating or panel) near5 (cathode or electrode))) and blind	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/20 17:07